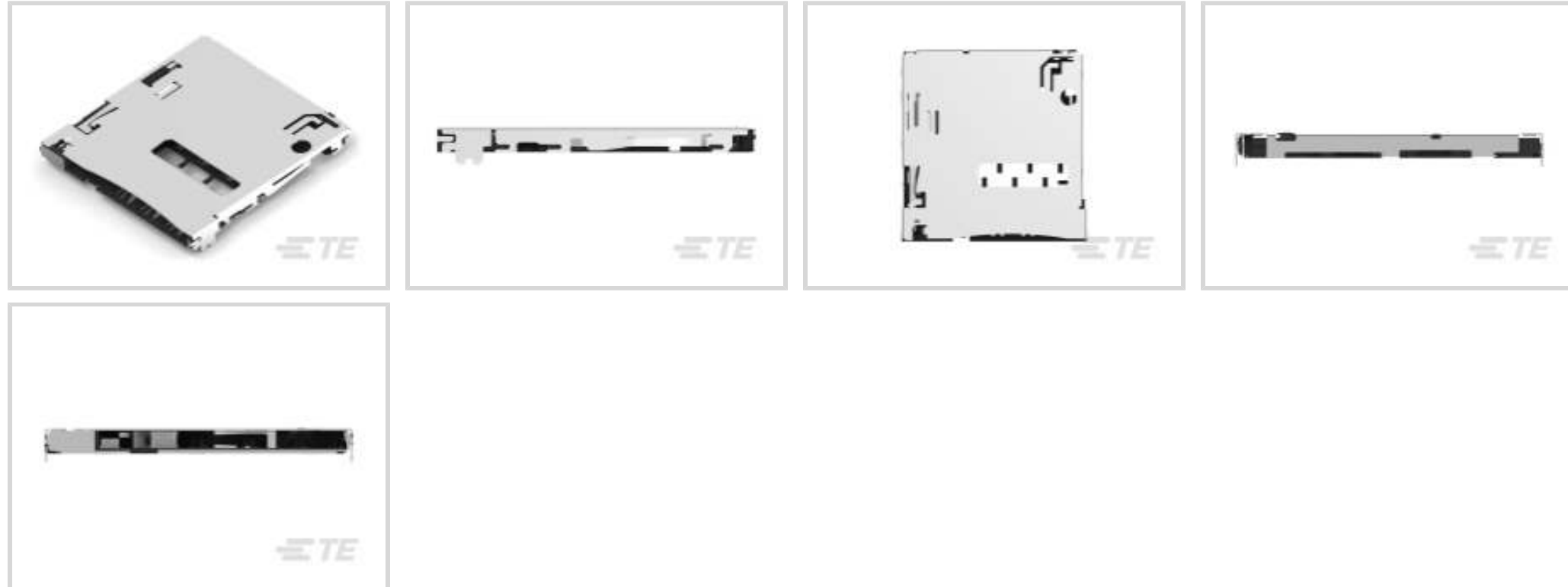




Connectors > PCB Connectors > Memory Card Connectors > SIM Card Connectors



Compatible Card: **SIM/SAM**  
 Number of Positions: **6**  
 Centerline (Pitch): **2.54 mm [.1 in]**  
 Number of Loaded Positions: **6**  
 Connector & Contact Terminates To: **Printed Circuit Board**

**Features**

**Product Type Features**

Compatible Card	SIM/SAM
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Number of Positions	6
Number of Loaded Positions	6

**Contact Features**

Contact Current Rating (Max)	.5 A
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**Termination Features**

Termination Method to Printed Circuit Board	Surface Mount
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**Mechanical Attachment**

Connector Mounting Type	Board Mount
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**Housing Features**

Centerline (Pitch)	2.54 mm[.1 in]
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**Usage Conditions**

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Operating Temperature Range	-30 – 85 °C[-22 – 185 °F]
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**Operation/Application**

Circuit Application	Signal
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**Product Compliance**

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

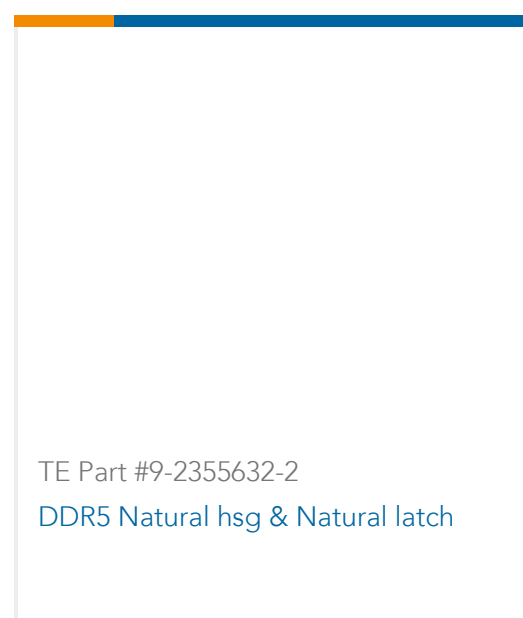
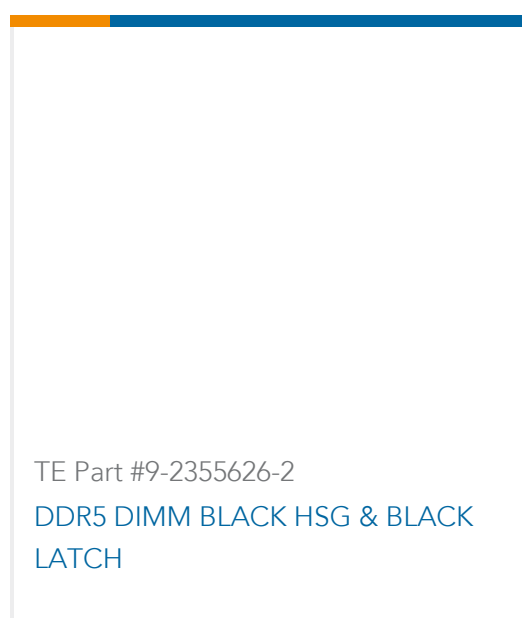
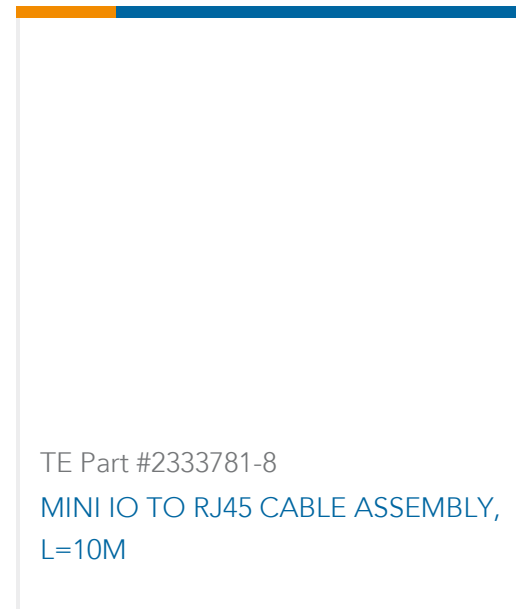
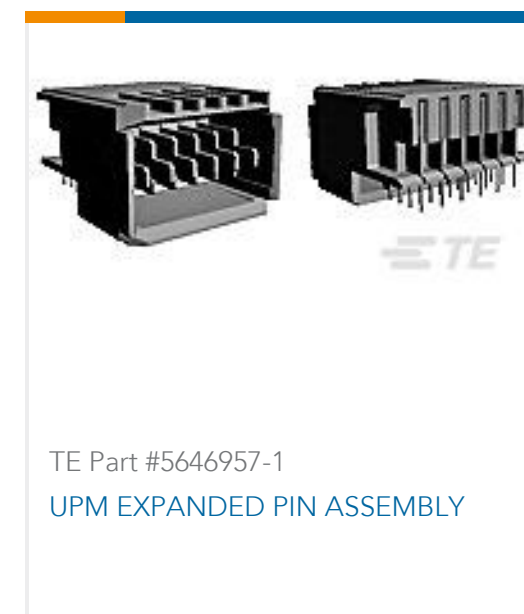
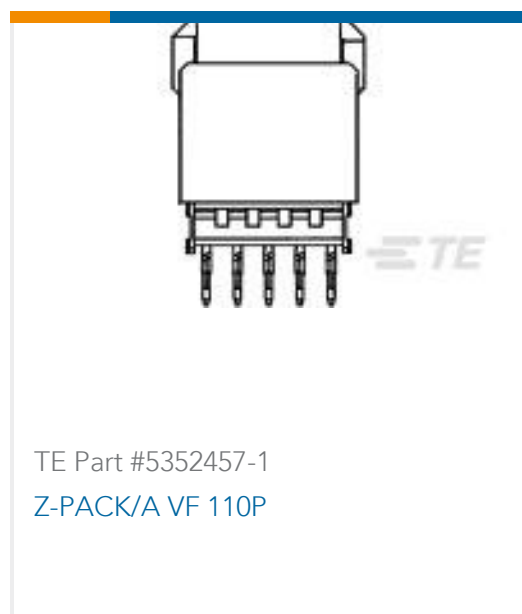
**Product Compliance Disclaimer**

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

**Compatible Parts**

 <p>TE Part # 2201778-1 MICRO SD PUSH PUSH LOW PROFILE TYPE</p>	 <p>TE Part # 1554901-1 SHIELD FINGER 2011 EMBOSS PACKING</p>	 <p>TE Part # 2309923-2 BLOCK SIM CONNECTOR SIDE ENTRY</p>	 <p>TE Part # 2336582-1 PUSH-PUSH NANO SIM CONNECTOR</p>
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**Customers Also Bought**



## Documents

### Product Drawings

#### PUSH-PUSH MICRO SIM CONNECTOR

English

### CAD Files

#### 3D PDF

3D

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2822541-1\\_C.2d\\_dxf.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2822541-1\\_C.3d\\_igs.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2822541-1\\_C.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

## Product Specifications



## Product Specification

English

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## Product Environmental Compliance

### TE Material Declaration

English